

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

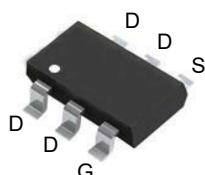
## Product Summary



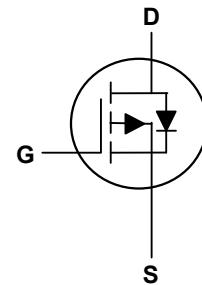
$V_{DS}$	-150	V
$I_D$	-1	A
$R_{DS(ON)}$ (at $V_{GS}=-10V$ )	1	$\Omega$
$R_{DS(ON)}$ (at $V_{GS}=-6V$ )	1.2	$\Omega$

## Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch



SOT23-6L Top View



## Absolute Maximum Ratings( $T_A=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	-150	V
Gate-Source Voltage	$V_{GS}$	$\pm 25$	V
Continuous Drain Current, $V_{GS} @ -10V^1$	$I_D @ T_A = 25^\circ\text{C}$	-1	A
Continuous Drain Current, $V_{GS} @ -10V^1$	$I_D @ T_A = 70^\circ\text{C}$	-0.78	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-4	A
Total Power Dissipation <sup>3</sup>	$P_D @ T_A = 25^\circ\text{C}$	2	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	62.5	$^\circ\text{C/W}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-150	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}$ , $I_D=-1\text{A}$	---	0.77	1	$\Omega$
		$V_{\text{GS}}=-6\text{V}$ , $I_D=-0.8\text{A}$	---	0.8	1.2	$\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = -250\mu\text{A}$	-1.2	-2	-4	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-120\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-25	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 25\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-10\text{V}$ , $I_D=-1\text{A}$	---	3.4	---	S
Total Gate Charge	$Q_g$	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-1\text{A}$	---	12	19.2	nC
Gate-Source Charge	$Q_{\text{gs}}$		---	2	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	2.5	---	
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-1\text{A}$	---	9	---	ns
Rise Time	$T_r$		---	5	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	24	---	
Fall Time	$T_f$		---	8	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	520	832	pF
Output Capacitance	$C_{\text{oss}}$		---	33	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	20	---	

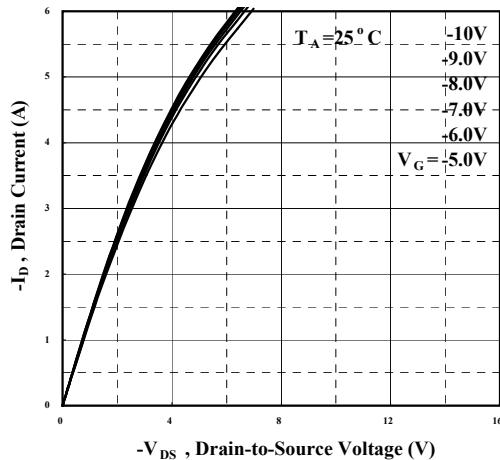
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_S=-1.5\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.3	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F=-1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	40	---	nS
	$Q_{\text{rr}}$		---	70	---	nC

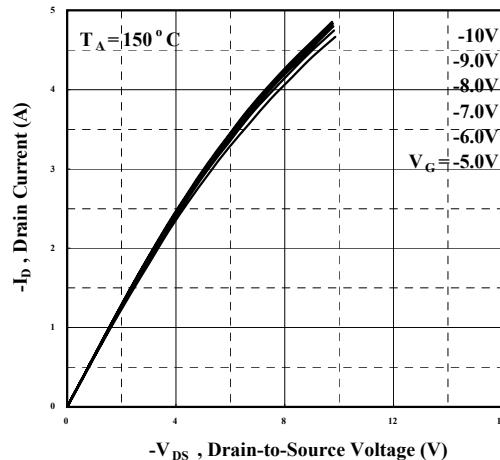
**Note:**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
3. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

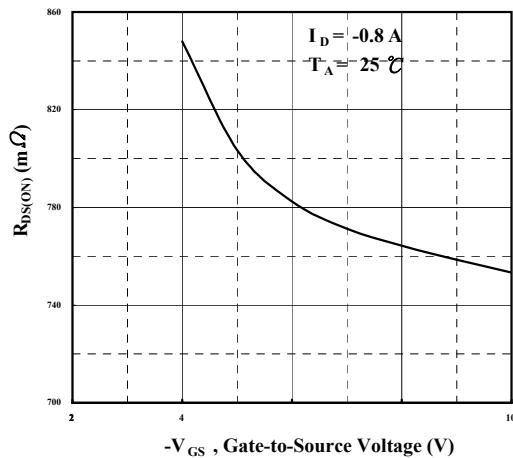
## Typical Characteristics



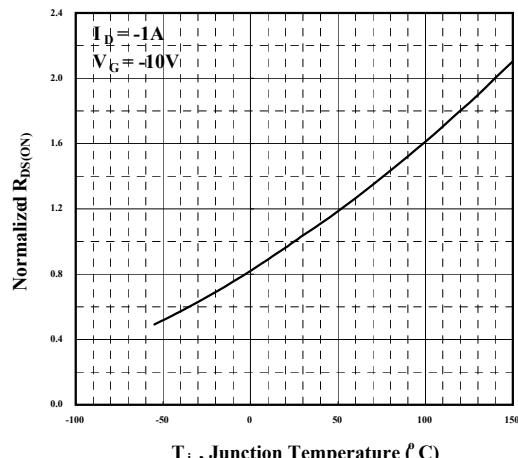
**Fig 1. Typical Output Characteristics**



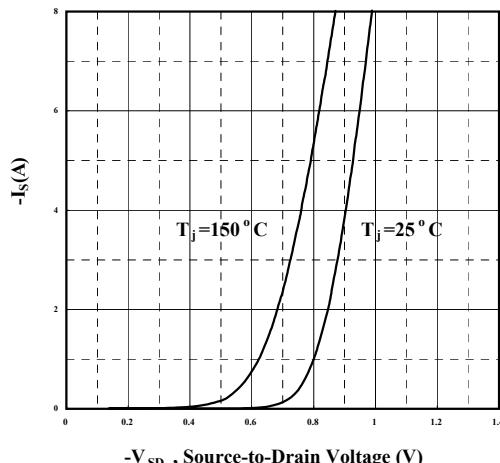
**Fig 2. Typical Output Characteristics**



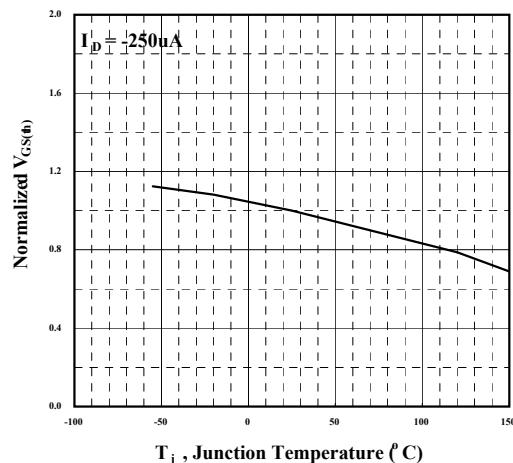
**Fig 3. On-Resistance v.s. Gate Voltage**



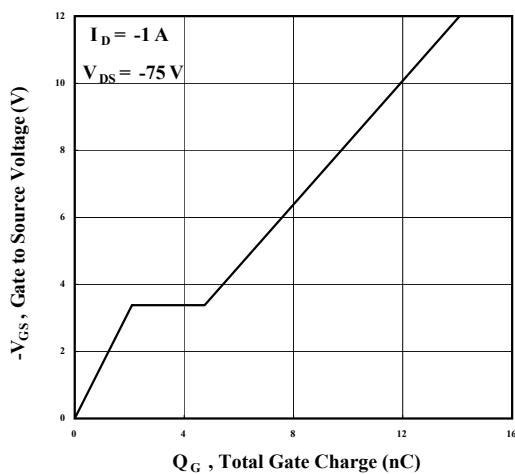
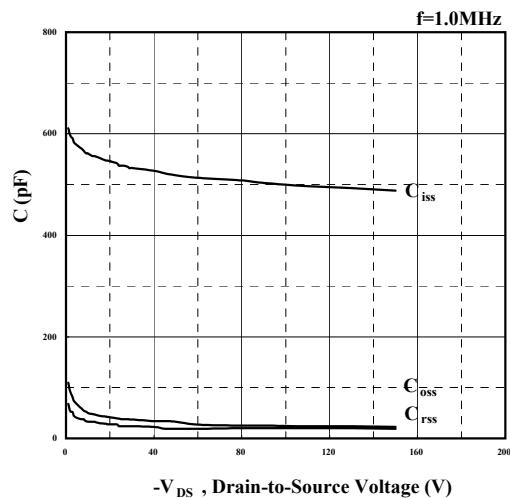
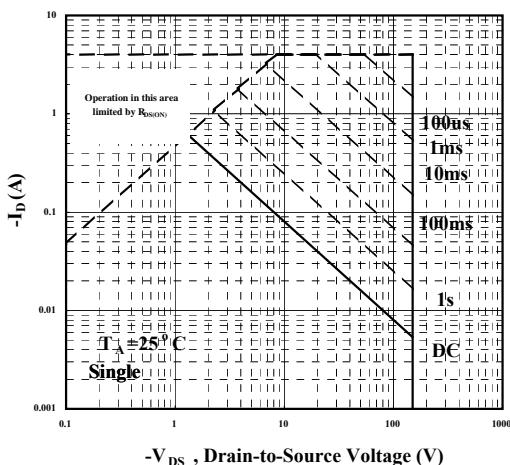
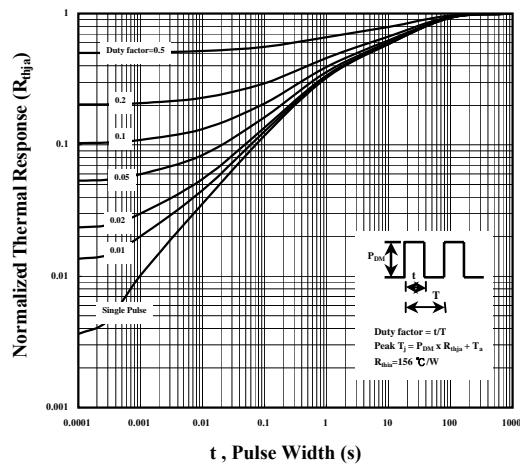
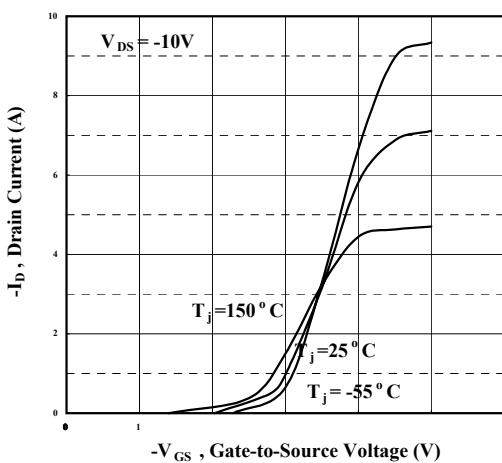
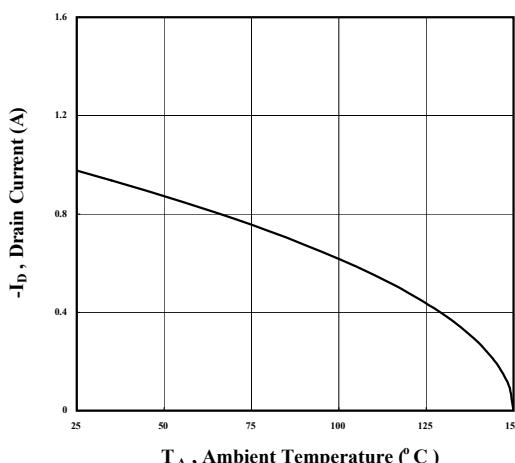
**Fig 4. Normalized On-Resistance v.s. Junction Temperature**

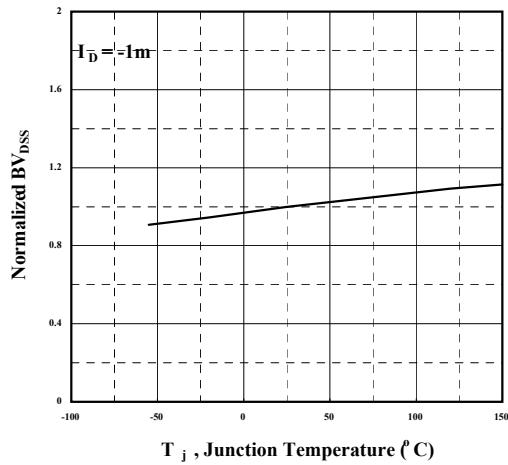


**Fig 5. Forward Characteristic of Reverse Diode**

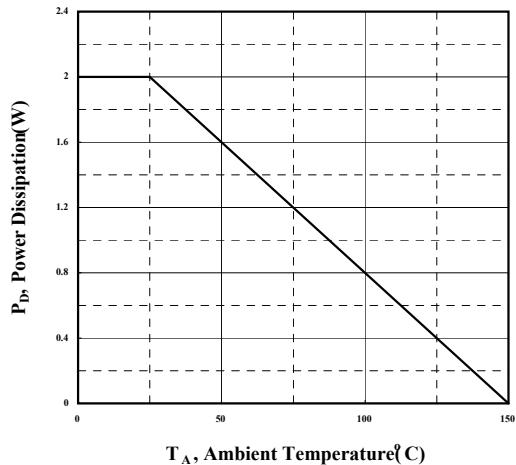


**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

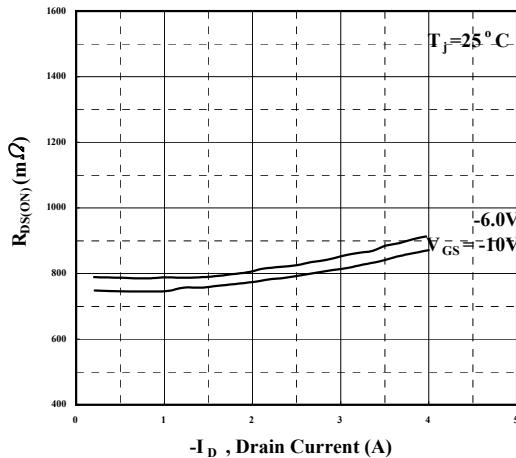

**Fig 7. Gate Charge Characteristics**

**Fig 8. Typical Capacitance Characteristics**

**Fig 9. Maximum Safe Operating Area**

**Fig 10. Effective Transient Thermal Impedance**

**Fig 11. Transfer Characteristics**

**Fig 12. Drain Current v.s. Ambient Temperature**



**Fig 13. Normalized  $BV_{DSS}$  v.s. Junction**

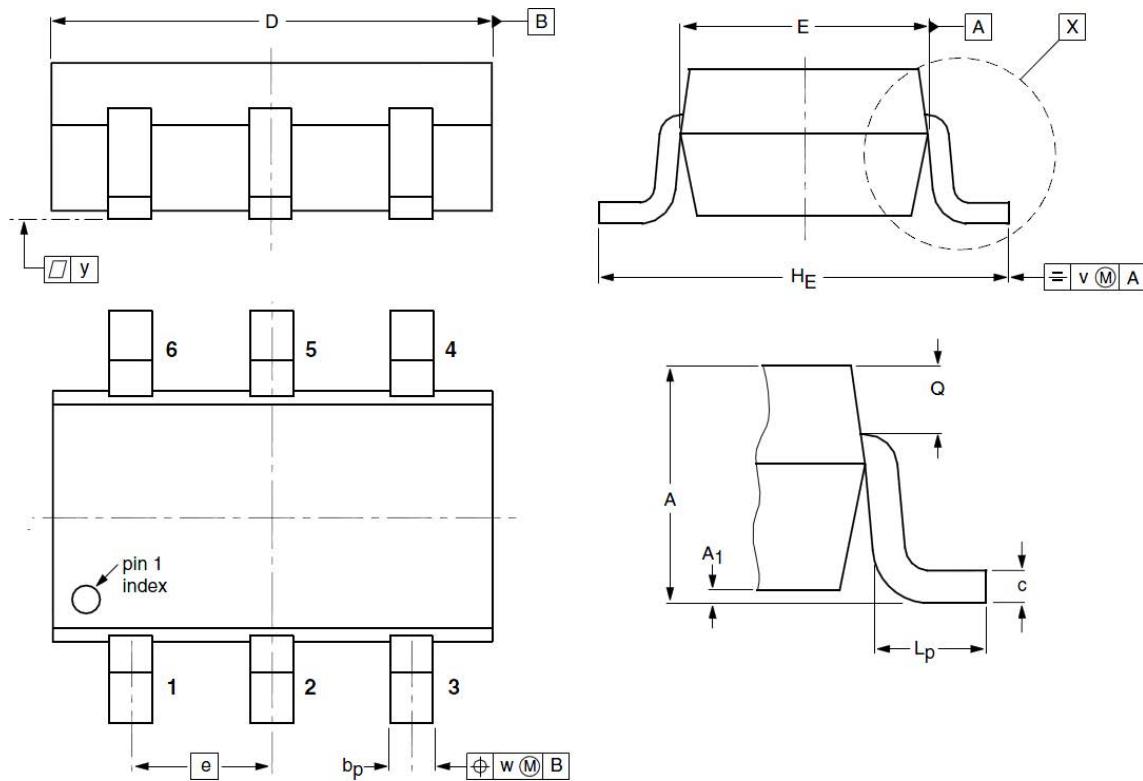


**Fig 14. Total Power Dissipation**



**Fig 15. Typ. Drain-Source on State  
Resistance**

### SOT23-6L Package Outline Dimensions



<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	0.90	1.07	1.45	<b>A<sub>1</sub></b>	0.01	0.05	0.15
<b>b<sub>p</sub></b>	0.30	0.40	0.50	<b>c</b>	0.10	0.15	0.22
<b>D</b>	2.70	2.92	3.10	<b>E</b>	1.35	1.55	1.75
<b>e</b>	--	0.95	--	<b>H<sub>E</sub></b>	2.50	2.80	3.00
<b>L<sub>p</sub></b>	0.30	0.45	0.60	<b>Q</b>	0.23	0.29	0.33
<b>v</b>	--	0.20	--	<b>W</b>	--	0.20	--
<b>y</b>	--	0.10	--				